



## Product Change Notification - LIAL-17UAOY777

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**Date:**

25 Mar 2020

**Product Category:**

Switchtec

**Affected CPNs:****Notification subject:**

CCB 4080 Cancellation Notice: For the qualification of STAK as an additional assembly site and WINS as an additional bumping facility for selected Microsemi PM857x, PM856x, PM854x, PM853x, PM855x device families available in 650L BBGA (27x27x2.79mm) package.

**Notification text:****PCN Status:**

Cancellation notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

This change would have affected the selected Microsemi PM857x, PM856x, PM854x, PM853x, PM855x device families available in 650L BBGA (27x27x2.79mm) package.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

This qualification was originally performed to qualify STAK as an additional assembly site and WINS as an additional bumping facility for selected Microsemi PM857x, PM856x, PM854x, PM853x, PM855x device families available in 650L BBGA (27x27x2.79mm) package.

**Impacts to Data Sheet:**

Not applicable

**Change Impact:**

Not applicable

**Reason for Change:**

Microchip has already issued a final notification as PCN number [LIAL-11GXQL417](#) for the qualification of STAK as an additional assembly site and WINS as an additional bumping facility for selected Microsemi products of the 28nm TSMC wafer technology available in 650L BBGA (27x27x2.79mm) package.

**Change Implementation Status:**

Not applicable

**Estimated First Ship Date:**

Not applicable

**Method to Identify Change:**

Not applicable

**Revision History:**

**January 3, 2020:** Issued initial notification.



**March 25, 2020:** Issued cancellation notification. Microchip has already issued a final notification as PCN number [LIAL-11GXQL417](#) for the qualification of STAK as an additional assembly site and WINS as an additional bumping facility for selected Microsemi products of the 28nm TSMC wafer technology available in 650L BBGA (27x27x2.79mm) package.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

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Affected Catalog Part Numbers (CPN)

PM8573B-F3EI  
PM8572B-F3EI  
PM8571B-F3EI  
PM8563B-F3EI  
PM8562B-F3EI  
PM8561B-F3EI  
PM8543B-F3EI  
PM8542B-F3EI  
PM8541B-F3EI  
PM8533B-F3EI  
PM8532B-F3EI  
PM8531B-F3EI  
PM8553B-F3EI  
PM8552B-F3EI  
PM8551B-F3EI